

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims: Claims 1-45 (Previously cancelled)

46. (Currently Amended) A double-sided printed wiring board comprising:
an insulator substrate having at least first and second generally
parallel surfaces and an unplated blind via extending from said
first surface, the unplated blind via having a sidewall;
a cured mass of a flowable conductive material extending over the
sidewall ~~first surface~~ and filling said unplated blind via and
having an end located adjacent to the first surface of said
insulator substrate; and
a conductive pad disposed over the cured mass of flowable conductive
material and being in electrical communication with the cured
mass of flowable conductive material.
47. (Previously presented) The board according to claim 46, wherein said
cured mass of flowable conductive material is selected from the group
consisting of conductive inks, conductive pastes, and conductive adhesives.

48. (Previously presented) The board according to claim 46, wherein said conductive pad comprises copper.

49. (Previously presented) The board according to claim 48, wherein said conductive pad has a thickness greater than 0.2 mils.

50. (Currently Amended) A printed circuit board (PCB) comprising:

a substrate having at least first and second generally parallel surfaces
and an unplated blind via extending from said first surface, the
unplated blind via having a sidewall;

a first conductive layer extending over the ~~first surface~~ sidewall and
the walls of the unplated blind via, such that said via still
maintains an opening, said first conductive material comprising
electrolytically deposited copper having a substantially uniform
thickness exceeding 0.2 mils;

~~a second conductive material disposed in said opening to substantially
fill said blind via; and~~

a ~~third~~ second conductive material disposed on said first conductive layer on said first surface., ~~and over the surface of said second conductive material in said opening.~~

51. (Currently Amended) The board according to claim 50, wherein said ~~second~~ first conductive material is cured flowable conductive material.

52. (Currently Amended) The board according to claim 51, wherein said ~~second~~ first conductive material is a conductive ink.

53. (Currently Amended) A circuit board comprising:

a substrate having at least first and second generally parallel surfaces
and an unplated blind via extending from the first surface, the
unplated blind via having a sidewall;

~~a first conductive layer extending over the first surface and the walls
of the through-hole via;~~

a conductive material positioned within and filling the unplated blind via; and

a second conductive layer extending over substantially all of the first ~~conductive layer on the first surface, and over~~ the conductive material positioned within the unplated blind via.

54. (Previously presented) The circuit board of claim 53 wherein the first and second surfaces are exterior surfaces of the substrate.

55. (Currently Amended) The circuit board of claim 53 wherein the first ~~conductive layer~~ conductive material comprises copper.

56. (Previously presented) The circuit board of claim 55 wherein the second conductive layer comprises copper.

57. (Currently Amended) The circuit board of claim 53 wherein the conductive material positioned within the unplated blind via is selected from the group consisting of conductive inks, conductive pastes, and conductive adhesives.

58. (Previously presented) The circuit board of claim 57 wherein the conductive material is a conductive ink.

59. (Previously presented) The circuit board of claim 58 wherein the conductive ink comprises at least one of silver, copper, and a noble metal.

60. (Currently Amended) The circuit board of claim 53 wherein the ~~first and second~~ conductive layer ~~layers~~ are is adapted to be etched to thereby form a conductive pad positioned on the conductive material plugging the unplated blind via.

61. (Currently Amended) The circuit board of claims 46, 50, or 53 wherein the unplated blind via is a buried via.

62. (Currently Amended) The circuit board of claims 46, 50, or 53 wherein the unplated blind via is a through-hole blind via.